

HDTF-4-08-S-RA-LC-100



HDTF-4-04-S-RA-LC-100

HDTF SERIES

(1.80 mm) .071"

XCede® HD BACKPLANE RECEPTACLE

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HDTF

- Insulator Material:** Liquid Crystal Polymer
- Contact Material:** Copper Alloy
- Plating:** Sn or Au over 50 μ" (1.27 μm) Ni
- Operating Temp Range:** -40 °C to +105 °C
- Current Rating:** Testing Now!
- RoHS Compliant:** Yes

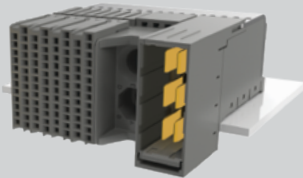
RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



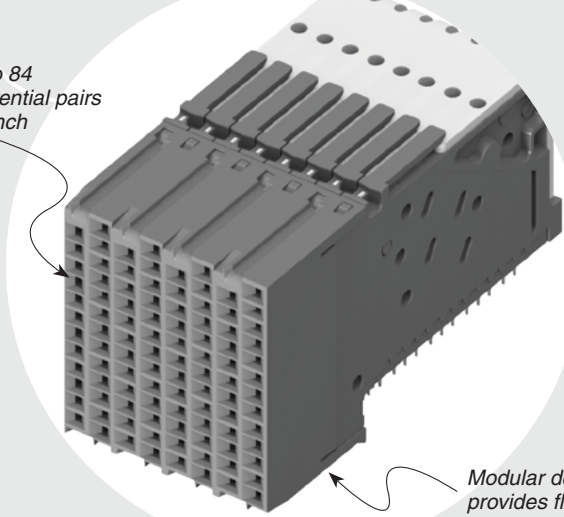
Mates with:
HDTM

ALSO AVAILABLE
(Customer Defined Configurations)



Power and keying/guidance modules also are available but require a single customizable BSP product. A BSP product is built by combining any number, in any configuration, of HDTFs, power and keying/guidance modules to create one receptacle. Contact HSBP@samtec.com for more information about building a BSP product.

Up to 84 differential pairs per inch



Modular design provides flexibility in applications

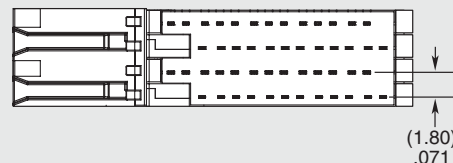
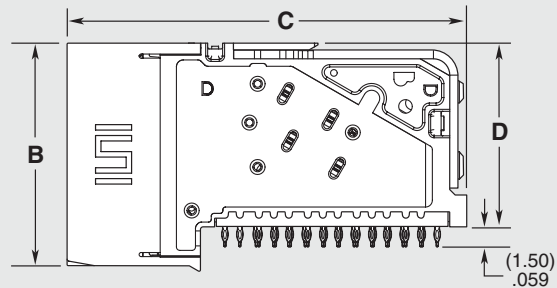
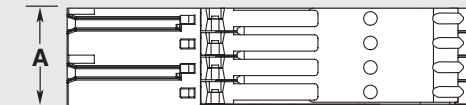
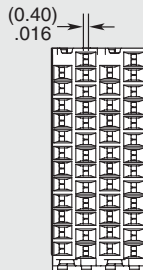
TOOLING

- For press-fit extraction and insertion tool options, visit www.samtec.com/tooling

HDTF	PAIRS PER COLUMN	NO. OF COLUMNS	PLATING	RA	WAFERS	IMPEDANCE
-3, -4, -6	= Pairs Per Column	-04 = Four Columns -06 = Six Columns -08 = Eight Columns	-S = 30 μ" (0.76 μm) Gold in contact area, Matte Tin on tail	-LC = Standard -HS = High-Speed	-100 = 100 Ω -085 = 85 Ω	

NO. OF COLUMNS	A
-04	(7.2) .28
-06	(10.8) .42
-08	(14.4) .57

PAIRS PER COLUMNS	B	C	D
-3	(12.8) .50	(26.0) 1.02	(9.80) .386
-4	(16.4) .64	(29.4) 1.16	(13.5) .53
-6	(23.6) .93	(36.6) 1.44	(20.7) .81



Note:
XCede® is a registered trademark of Amphenol.

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications. Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.